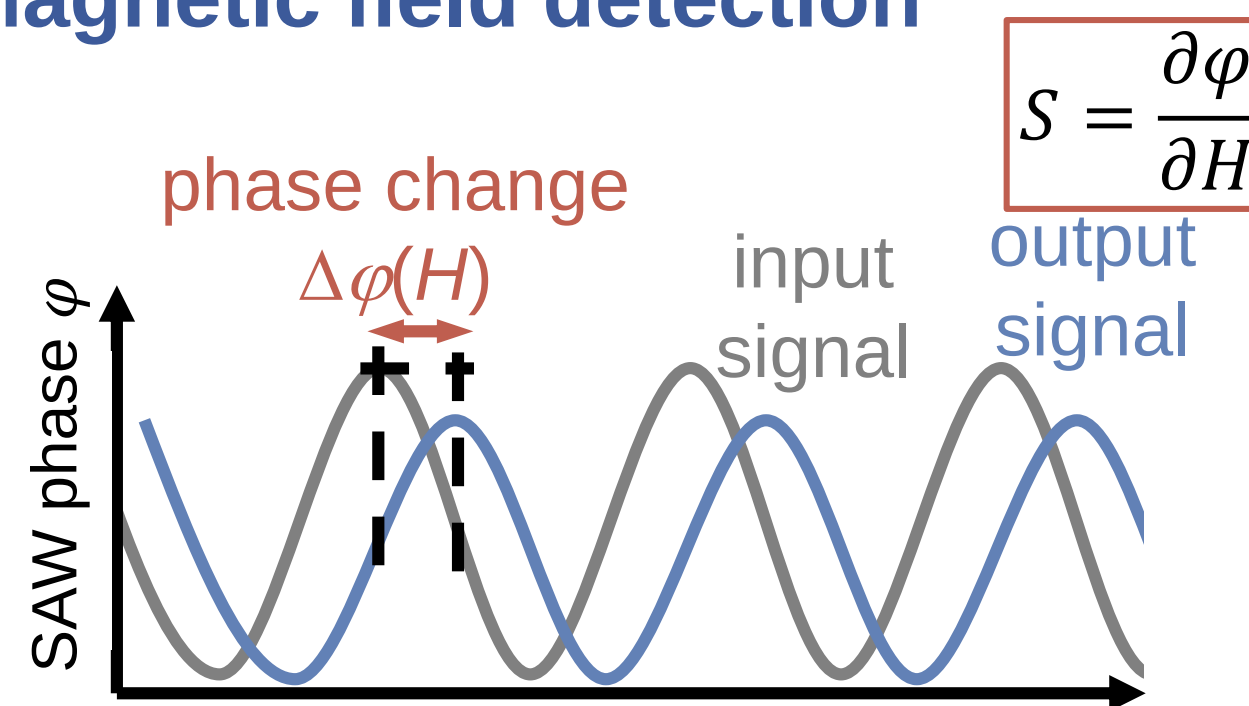
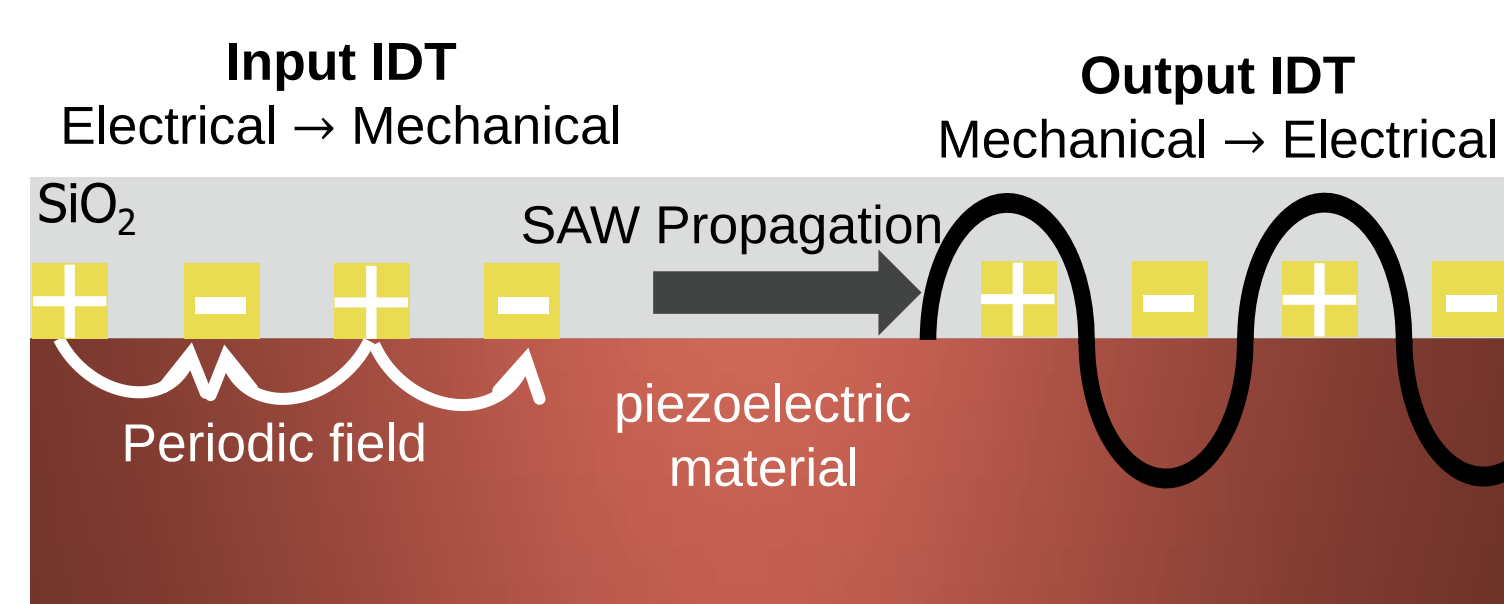


Motivation and Objectives

Surface Acoustic Wave (SAW) Sensor

Advantages: high bandwidth
→ many application scenarios
Miniaturization possible
SAW Generation

Challenges: High frequencies
→ new film developments
→ electronics development
Magnetic field detection



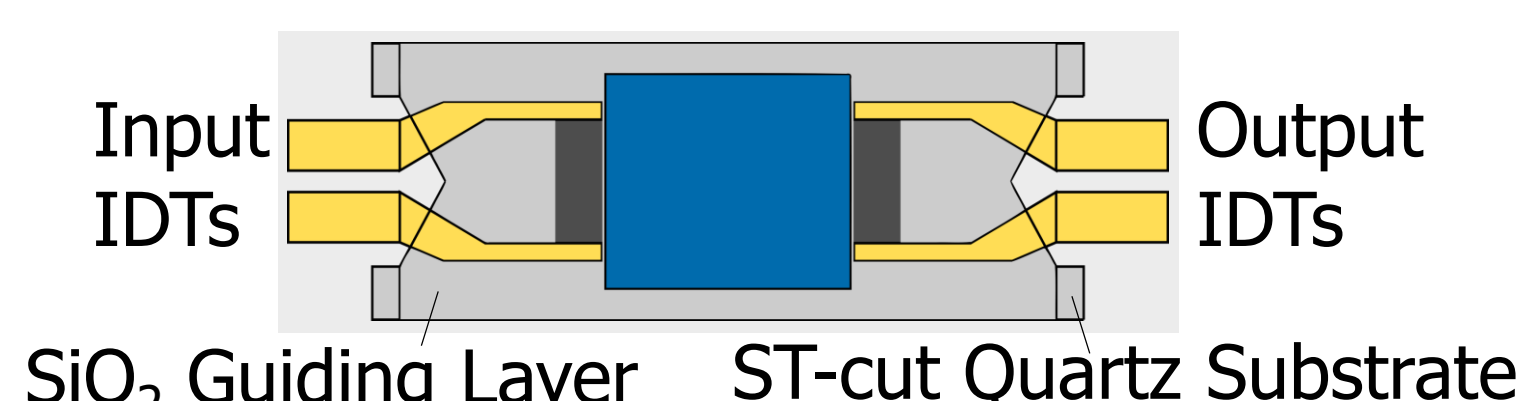
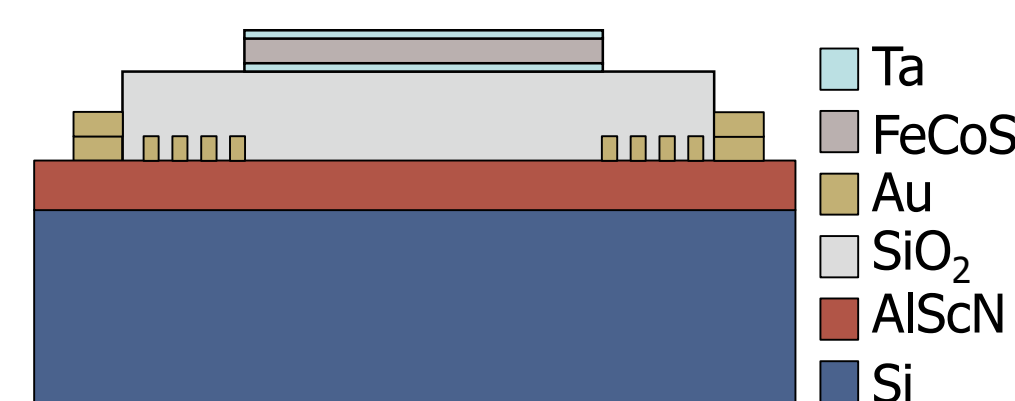
Measurement principle is based on the magneto-elastically induced change of Young's modulus of the magnetostrictive layer (ΔE effect).

Thin-film AlScN SAW sensor (ISIT)

- AlScN on 200 mm Si wafers
- CMP smoothed SiO₂ (several SAW modes)
- single layer (Fe₉₀Co₁₀)₇₈Si₁₂B₁₀

Single Crystal SAW sensor (CAU)

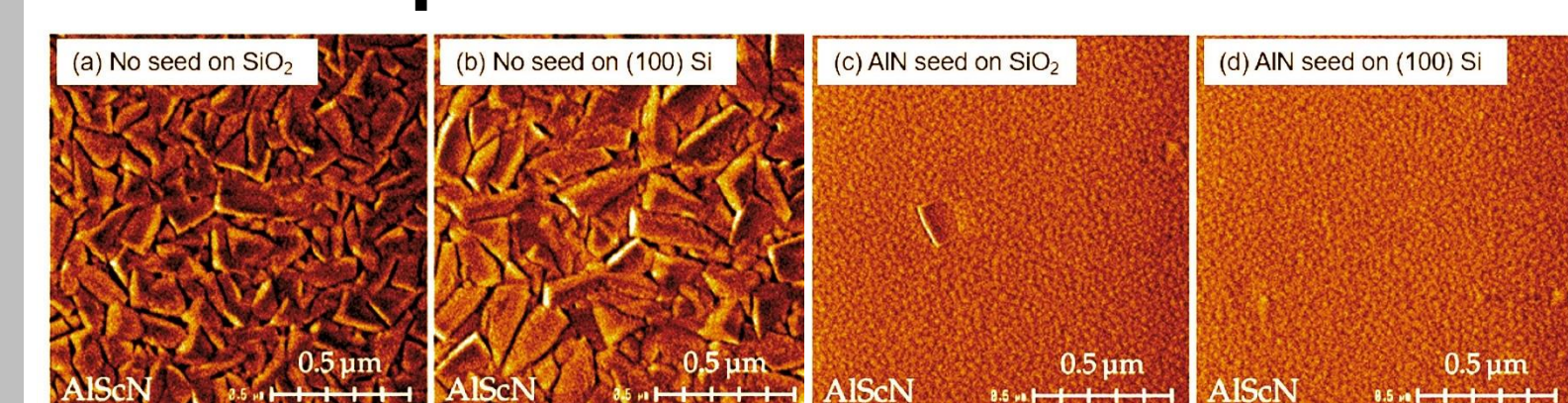
- Piezoelectric substrate
- SiO₂ guiding layer (**Love wave**)
- exchange biased (Fe₉₀Co₁₀)₇₈Si₁₂B₁₀



Results of the Second Funding Period

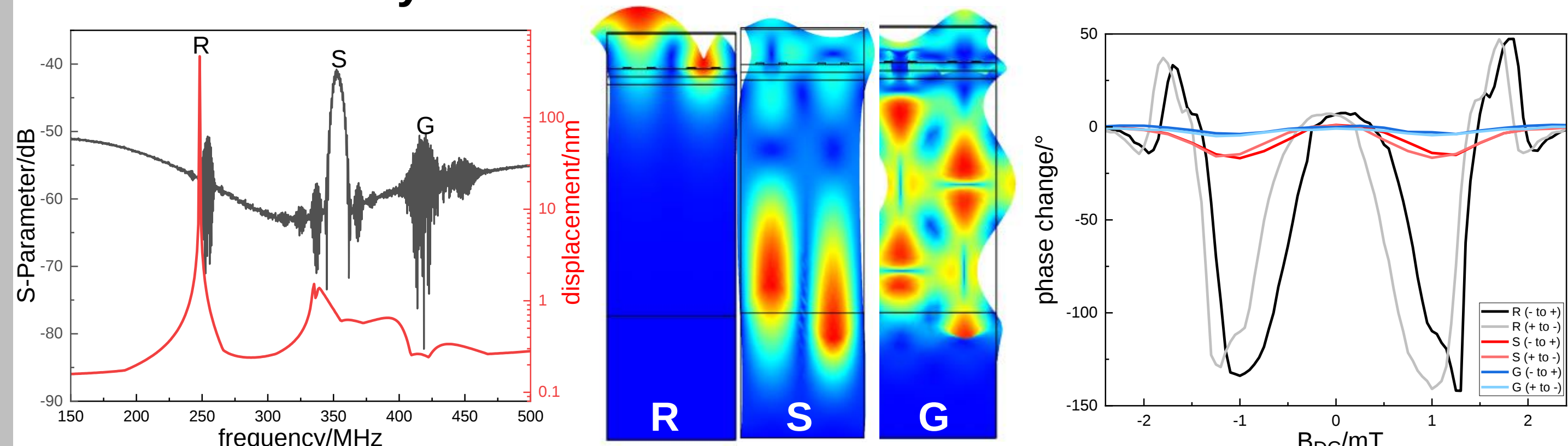
Thin film AlScN SAW sensor (ISIT)

AlScN deposition on Si



AlN seed layer significantly increases the layer growth (c-axis quality, piezo-acoustic coupling) [A9-4]

SAW modes in layered SAW structures



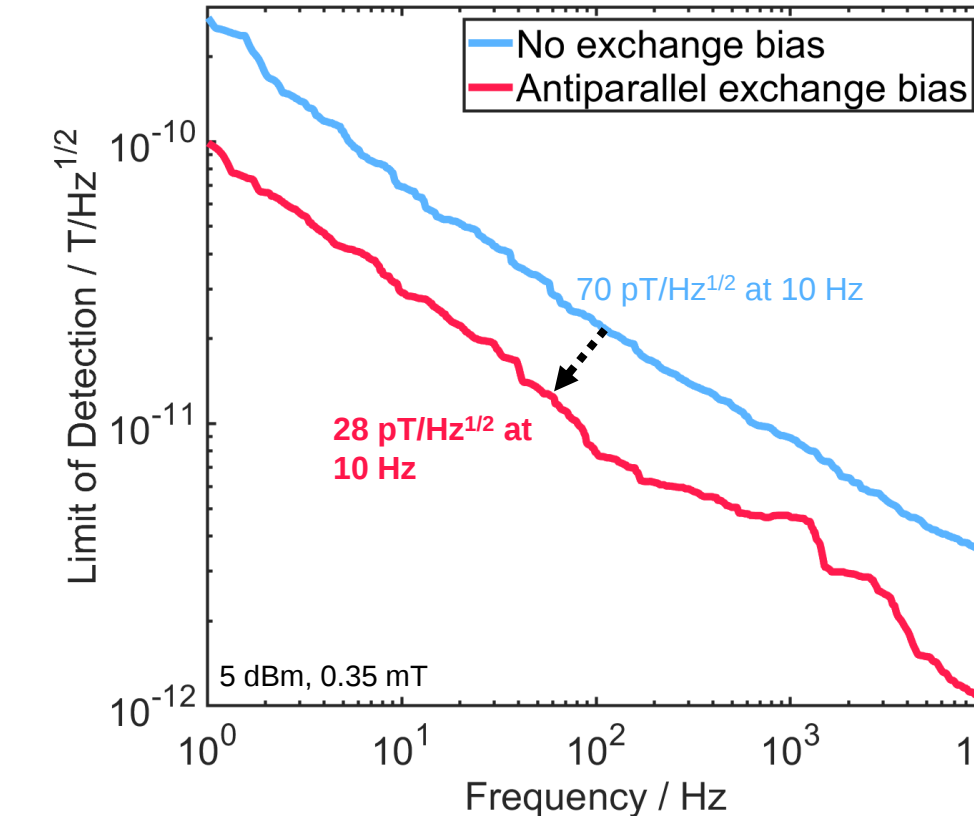
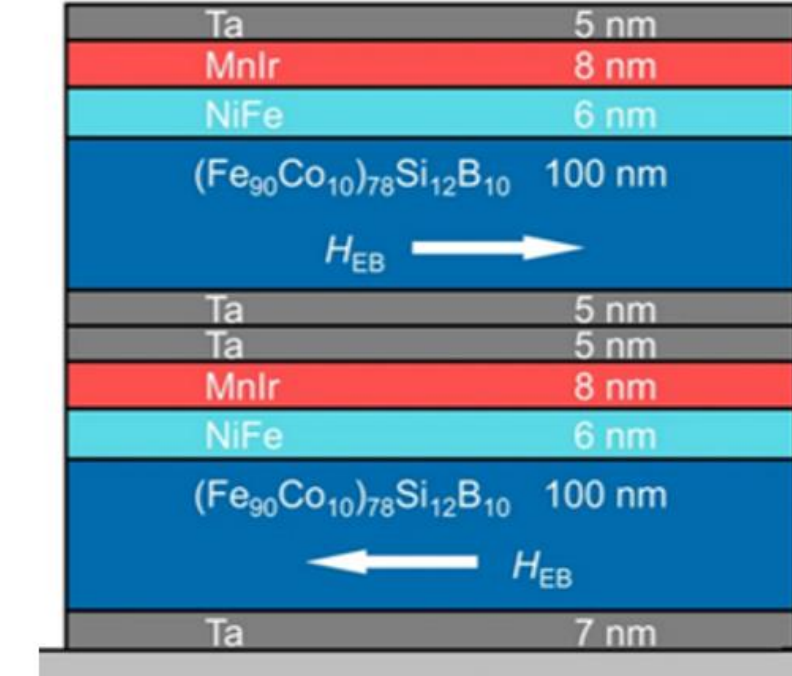
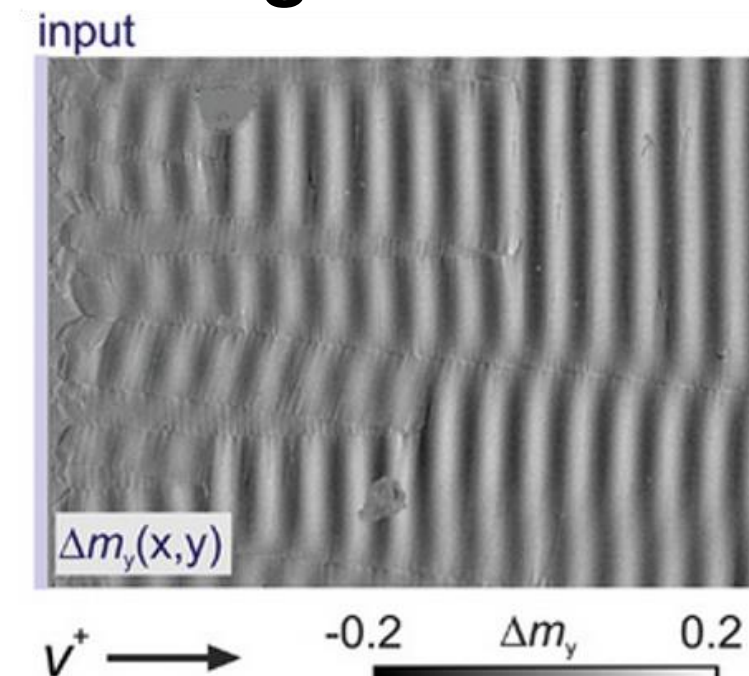
The **Rayleigh (R)** mode, **Sezawa (S)** mode and other higher order **guided (G)** modes are observed and investigated for magnetic field sensing.

Sensor performance with single layer FeCoSiB

Sensitivity: 1200 °/mT **LoD:** 350 pT/Hz^{1/2} at 10 Hz

Single Crystal SAW sensor (CAU)

Exchange bias



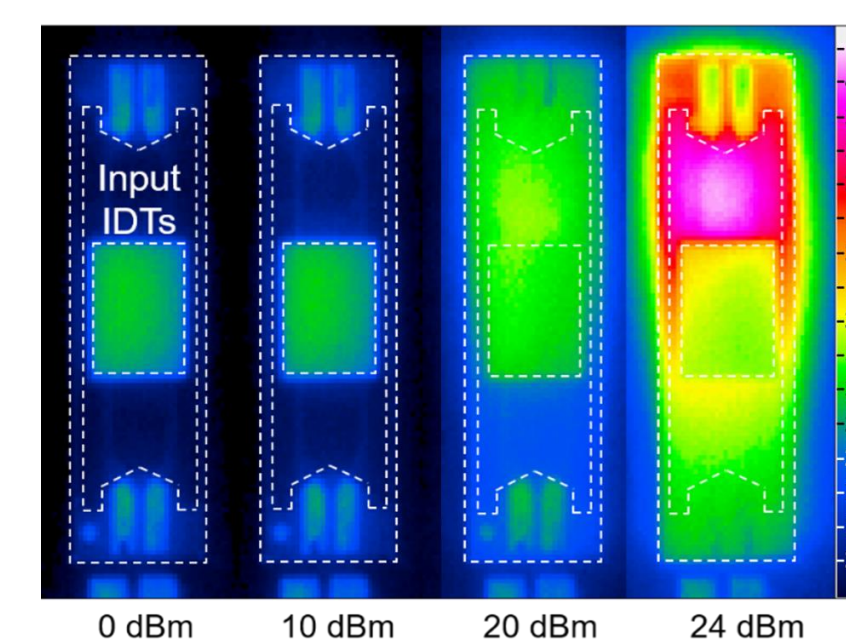
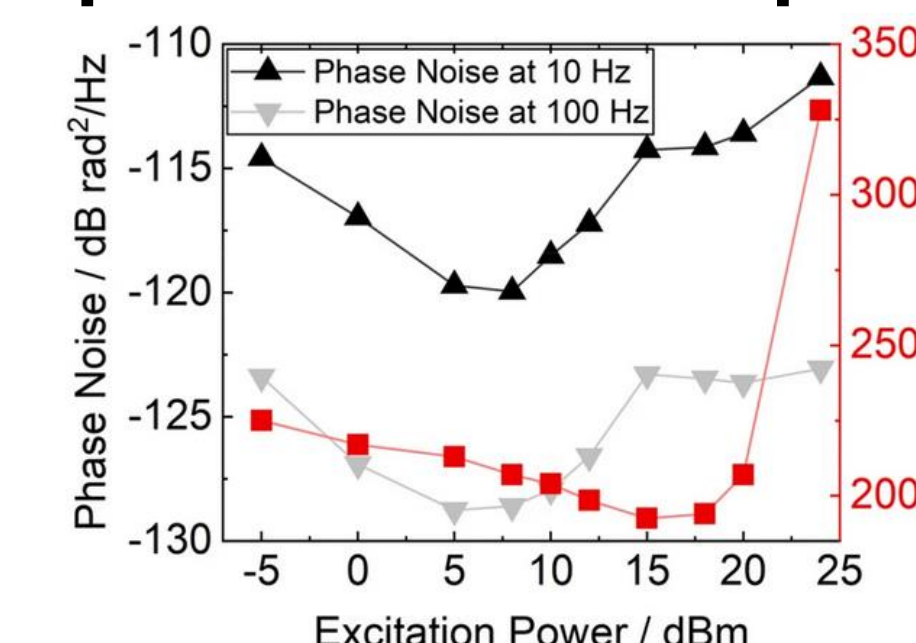
Domain walls

→ wavefront dephasing
→ major noise source

Anti parallel exchange bias → one domain

2.5x LoD improvement [A9-3, A9-7]

Optimal excitation power



Sensitivity and phase noise depend on excitation power

Lowest LoD at 5dBm [A9-7]

Work Plan for Third Funding Period

Research methods: Clean room fabrication



1000 qm ISIT cleanroom



300 qm CAU cleanroom

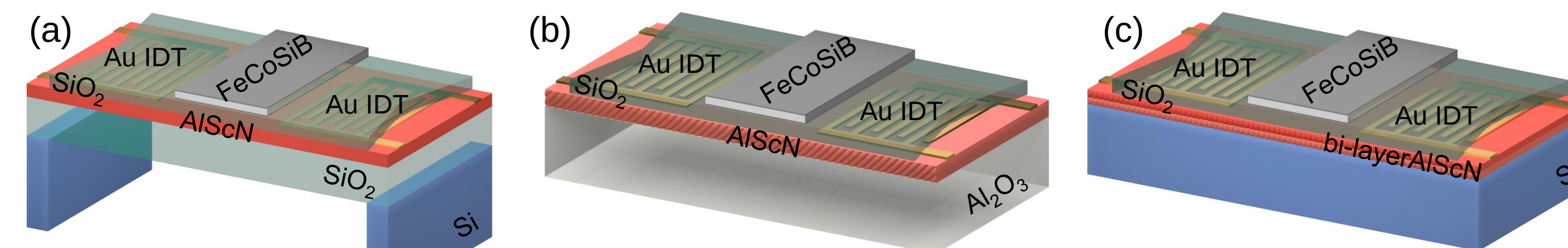
- SAW fabrication
- Functional characterization
- Structural characterization

Work plan

WP1 Magnetic multilayer stacks

- Enhance exchange bias stacks for thin film SAW
- Anisotropy alignment for bias-free operation

WP2 – Thin-film SAW



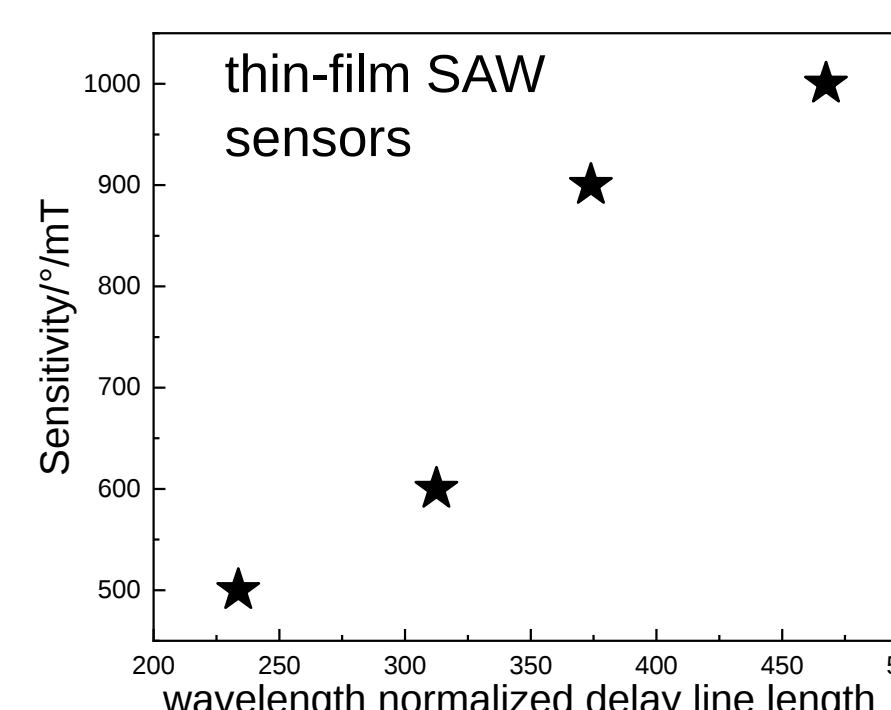
Backside substrate etch

AlScN grown with tilted c-axis on sapphire

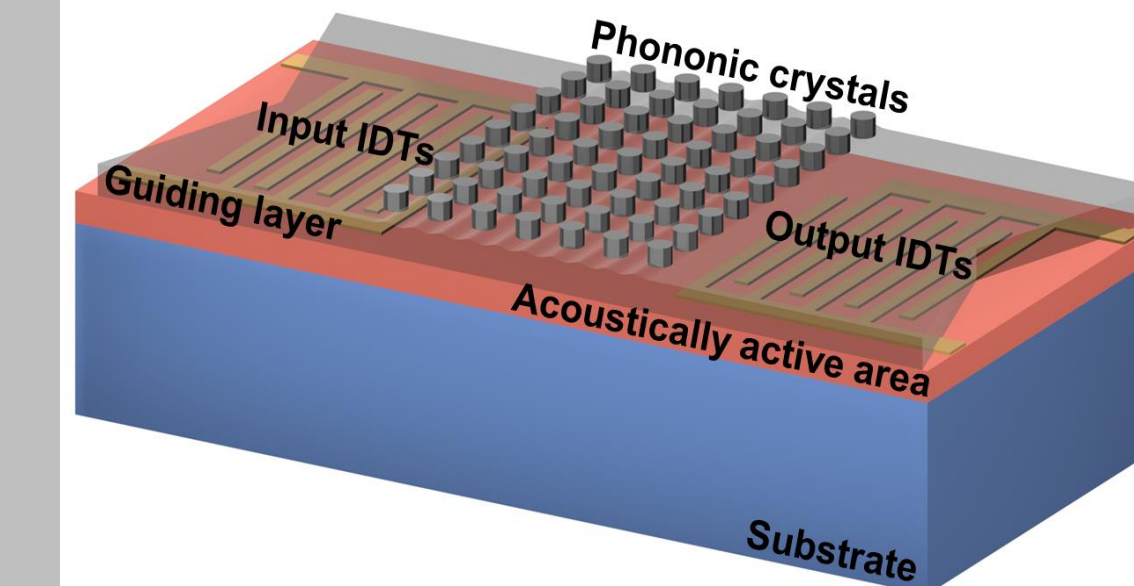
AlScN bi-layer grown on a Si substrate

WP3 Single Crystal SAW

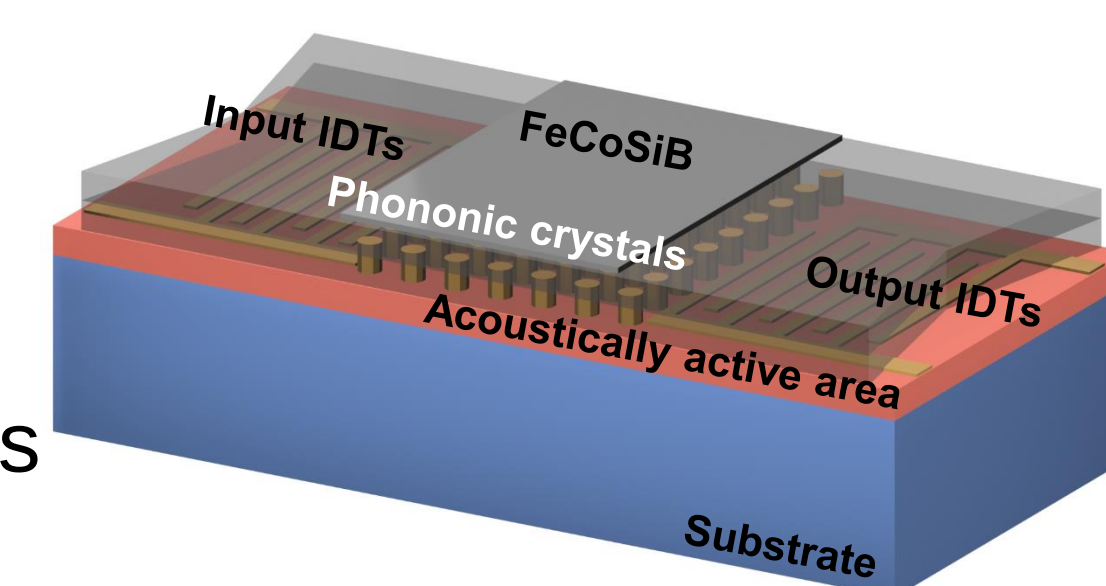
- Research on optimal SAW carrier frequency for the LOD
- Sensitivity improves at higher frequency
- Noise increases near ferromagnetic resonance?



WP4 Phononic Crystals



Different approaches to fabricate phononic crystals

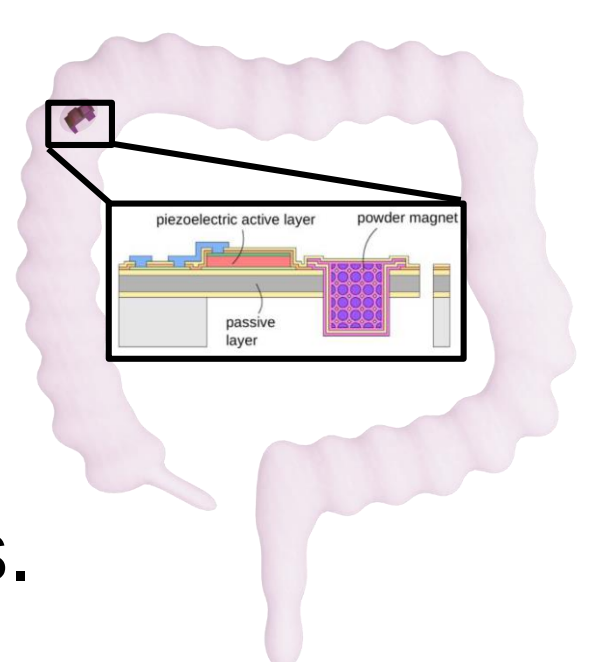


Improving sensitivity by creating resonant modes aligned with SAW modes resulting in enhanced interaction. [A9-10]

WP5 Integration in biomedical application

- Providing sensors and measurement expertise
- SAW perfect fit due the broadband capabilities

B13(N): Localization of current wireless motility capsules.



		2024		2025		2026		2027		2028	
		3	4	1	2	3	4	1	2	3	4
ISIT CAU Both	WP1 – Magnetic multi-layer stacks										
	Exchange bias										
WP2 – Thin-film SAW	Zero bias										
	Acoustic layer										
	Substrate variations										
WP3 – Single Crystal SAW	Application magnetic stacks										
	Frequency investigation										
	Design variation										
WP4 – Phononic crystals (PnC)	Application magnetic stacks										
WP5 – Integration in biomedical application											

Collaborations

A1: Application of advanced magnetic multilayers to SAW sensors

A6: Chemical and structural analysis of AlScN, synchrotron measurements

A8: Modeling of SAW sensor parameters and designs and phononic crystal

A10: Numerical studies on noise and phononic crystals

B1: Analog electronics, noise floor characterization, LOD measurements

B12(N), B13(N): Providing SAW sensors and measurement knowledge

Z1: Support in SAW sensor fabrication

Z2: Support with sensor characterization

Participation in focus groups

F1: Magnetic Layers

F3: Comparison of Sensor Concepts

F4: Magnetoelectric Sensors

Funds Requested

2 Doctoral researchers, consumables: 66 k€

[A9-1] Schell, V., Müller, C., Durdaut, P., Kittmann, A., Thormählen, L., Lofink, F., Meyners, D., Höft, M., McCord, J., & Quandt, E. (2020). Applied Physics Letters, 116(7).

[A9-2] Moench, S., Meyer, J. M., Zukauskaitė, A., Lebedev, V., Fichtner, S., Su, J., Niekief, F., Giese, T., Thormählen, L., Quandt, E., & Lofink, F. (2022). IEEE Sensors Letters, 6(10), 1–4.

[A9-3] Müller, C., Durdaut, P., Holländer, R. B., Kittmann, A., Schell, V., Meyners, D., Höft, M., Quandt, E., & McCord, J. (2022). Advanced Electronic Materials, 8(6), Article 2200033.

[A9-4] Su, J., Fichtner, S., Ghori, M. Z., Wolff, N., Islam, M. R., Lotnyk, A., Kaden, D., Niekief, F., Kienle, L., Wagner, B., & Lofink, F. (2022). Micromachines, 13(5).

[A9-5] Meyer, J. M., Schell, V., Su, J., Fichtner, S., Yarar, E., Niekief, F., Giese, T., Kittmann, A., Thormählen, L., Lebedev, V., Moench, S., Zukauskaitė, A., Quandt, E., & Lofink, F. (2021). Sensors, 21(24).

[A9-6] Wolff, N., Fichtner, S., Haas, B., Islam, M. R., Niekief, F., Kessel, M., Ambacher, O., Koch, C., Wagner, B., Lofink, F., & Kienle, L. (2021). Journal of Applied Physics, 129(3), Article 034103.

[A9-7] Schell, V., Spetzler, E., Wolff, N., Kienle, L., McCord, J., Quandt, E., & Meyners, D. (2023). Scientific Reports, 13(1), 8446.

[A9-8] Kittmann, A., Müller, C., Durdaut, P., Thormählen, L., Schell, V., Niekief, F., Lofink, F., Meyners, D., Knöchel, R., Höft, M., McCord, J., & Quandt, E. (2020). Sensors and Actuators a: Physical, 311, 111998.

[A9-9] Durdaut, P., Müller, C., Kittmann, A., Schell, V., Quandt, E., Knöchel, R., Höft, M., & McCord, J. (2021). Sensors, 21(16).

[A9-10] Samadi, M., Schmalz, J., Meyer, J. M., Lofink, F., Gerken, M. (2023). Micromachines, 14(11), 2130.

[A9-P1] Kittmann, A.; Zabel, S.; Yarar, E.; Faupel, F.; Knöchel, R.; Höft, M.; Durdaut, P.; Quandt, E.: DE 10 2016 123 274 B4

[A9-P2] Fichtner, S.; Kaden, D.; Wagner, B.; Lofink, F.: DE 10 2018 203812